

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	28690	epoxy with mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:03
L2	3579	1 same (pcb (printed adj circuit) circuit ic microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:19
L3	128	2 same etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:01
L4	2	3 same (mark\$4 demark\$4 de-mark\$4 fiducial)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:01
L5	1850	epoxy with mold\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:03
L6	75	5 and etch\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:19
L7	3321	mold\$4.clm. and etch\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:19
L8	711	7 and (pcb (printed adj circuit) circuit ic microelectronic).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:20
L9	27	8 and clean\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/07/04 13:20